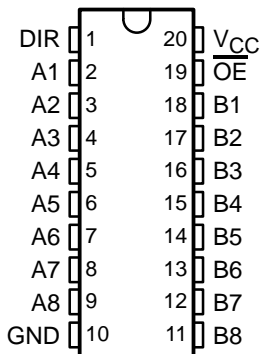


SN54ALS245A, SN54AS245, SN74ALS245A, SN74AS245 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

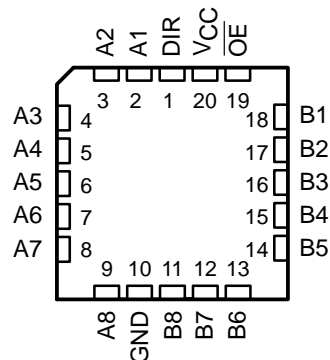
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- 4.5-V to 5.5-V V_{CC} Operation
- Max t_{pd} of 5.5 ns at 5 V
- 3-State Outputs Drive Bus Lines Directly
- pnp Inputs Reduce dc Loading

SN54ALS245A . . . J OR W PACKAGE
SN54AS245 . . . J PACKAGE
SN74ALS245A . . . DB, DW, N, OR NS PACKAGE
SN74AS245 . . . DW, N, OR NS PACKAGE
(TOP VIEW)



SN54ALS245A, SN54AS245 . . . FK PACKAGE
(TOP VIEW)



description/ordering information

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
0°C to 70°C	PDIP – N	Tube	SN74ALS245A-1N	SN74ALS245A-1N	
			SN74ALS245AN	SN74ALS245AN	
			SN74AS245N	SN74AS245N	
	SOIC – DW	Tube	SN74ALS245ADW	ALS245A	
			SN74ALS245ADWR		
			Tape and reel	SN74ALS245A-1DW	ALS245A-1
				SN74ALS245A-1DWR	
			Tube	SN74AS245DW	AS245
				SN74AS245DWR	
	SOP – NS	Tape and reel	SN74ALS245ANSR	ALS245A	
SN74ALS245A-1NSR			ALS245A-1		
SN74AS245NSR			74AS245		
SSOP – DB	Tape and reel	SN74ALS245ADBR	G245A		
		CDIP – J	Tube	SNJ54ALS245AJ	SNJ54ALS245AJ
				SNJ54AS245J	SNJ54AS245J
CFP – W	Tube	SNJ54ALS245AW	SNJ54ALS245AW		
		LCCC – FK	Tube	SNJ54ALS245AFK	SNJ54ALS245AFK
				SNJ54AS245FK	SNJ54AS245FK
-55°C to 125°C	LCCC – FK	Tube	SNJ54ALS245AFK	SNJ54ALS245AFK	
			SNJ54AS245FK	SNJ54AS245FK	



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

SN54ALS245A, SN54AS245, SN74ALS245A, SN74AS245 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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description/ordering information(continued)

These octal bus transceivers are designed for asynchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

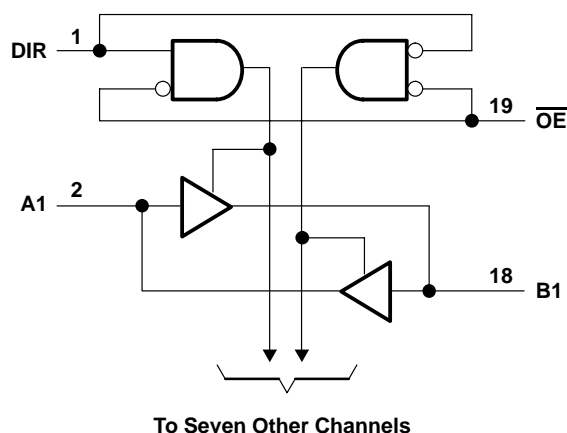
The devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending upon the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so that the buses are effectively isolated.

The -1 version of the SN74ALS245A is identical to the standard version, except that the recommended maximum I_{OL} is increased to 48 mA. There is no -1 version of the SN54ALS245A.

FUNCTION TABLE

INPUTS		OPERATION
\overline{OE}	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

logic diagram, each gate (positive logic)



absolute maximum ratings over operating free-air temperature range (SN54ALS245A, SN74ALS245A) (unless otherwise noted)†

Supply voltage, V_{CC}	7 V
Input voltage, V_I : All inputs	7 V
I/O ports	5.5 V
Package thermal impedance, θ_{JA} (see Note 1): DB package	70°C/W
DW package	58°C/W
N package	69°C/W
NS package	60°C/W
Storage temperature range	-65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.



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SN54ALS245A, SN54AS245, SN74ALS245A, SN74AS245 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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recommended operating conditions (see Note 2)

		SN54ALS245A			SN74ALS245A			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.7			0.8	V
I_{OH}	High-level output current			-12			-15	mA
I_{OL}	Low-level output current			12			24	mA
							48†	
T_A	Operating free-air temperature	-55		125	0		70	°C

† Applies only to the -1 version and only if V_{CC} is between 4.75 V and 5.25 V

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54ALS245A			SN74ALS245A			UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}		$V_{CC} = 4.5$ V,	$I_I = -18$ mA			-1.5			-1.5	V
V_{OH}		$V_{CC} = 4.5$ V to 5.5 V,	$I_{OH} = -0.4$ mA	$V_{CC} - 2$			$V_{CC} - 2$			V
		$V_{CC} = 4.5$ V	$I_{OH} = -3$ mA	2.4	3.2	2.4	3.2			
			$I_{OH} = -12$ mA	2						
			$I_{OH} = -15$ mA			2				
V_{OL}		$V_{CC} = 4.5$ V	$I_{OL} = 12$ mA	0.25	0.4	0.25	0.4	V		
			$I_{OL} = 24$ mA			0.35	0.5			
			$I_{OL} = 48$ mA†			0.35	0.5			
I_I	Control inputs	$V_{CC} = 5.5$ V	$V_I = 7$ V			0.1		0.1	mA	
	A or B ports		$V_I = 5.5$ V			0.1		0.1		
I_{IH}	Control inputs	$V_{CC} = 5.5$ V,	$V_I = 2.7$ V			20		20	μA	
	A or B ports§					20		20		
I_{IL}	Control inputs	$V_{CC} = 5.5$ V,	$V_I = 0.4$ V			-0.1		-0.1	mA	
	A or B ports§					-0.1		-0.1		
I_{O}^{\parallel}		$V_{CC} = 5.5$ V,	$V_O = 2.25$ V	-20		-112	-30		-112	mA
I_{CC}		$V_{CC} = 5.5$ V	Outputs high	30	48	30	45	mA		
			Outputs low	36	60	36	55			
			Outputs disabled	38	63	38	58			

† Applies only to the -1 version and only if V_{CC} is between 4.75 V and 5.25 V

‡ All typical values are $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$.

§ For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.

¶ The output conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit output current, I_{OS} .



SN54ALS245A, SN54AS245, SN74ALS245A, SN74AS245 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R ₁ = 500 Ω, R ₂ = 500 Ω, T _A = MIN to MAX†				UNIT
			SN54ALS245A		SN74ALS245A		
			MIN	MAX	MIN	MAX	
t _{PLH}	A or B	B or A	1	19	3	10	ns
t _{PHL}			1	14	3	10	
t _{PZH}	\overline{OE}	A or B	2	30	5	20	ns
t _{PZL}			2	29	5	20	
t _{PHZ}	\overline{OE}	A or B	2	14	2	10	ns
t _{PLZ}			2	30	4	15	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (SN54AS245, SN74AS245) (unless otherwise noted)‡

Supply voltage, V _{CC}	7 V
Input voltage, V _I : All inputs	7 V
I/O ports	5.5 V
Package thermal impedance, θ _{JA} (see Note 1): DW package	58°C/W
N package	69°C/W
NS package	60°C/W
Storage temperature range	–65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 2)

		SN54AS245			SN74AS245			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V _{IH}	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.8			0.8	V
I _{OH}	High-level output current			–12			–15	mA
I _{OL}	Low-level output current			48			64	mA
T _A	Operating free-air temperature	–55		125	0		70	°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



SN54ALS245A, SN54AS245, SN74ALS245A, SN74AS245 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SDAS272A – NOVEMBER 1994 – REVISED JANUARY 2003

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN54AS245		SN74AS245		UNIT	
			MIN	TYP†	MAX	MIN		TYP†
V_{IK}	$V_{CC} = 4.5\text{ V}$, $I_I = -18\text{ mA}$		-1.2		-1.2		V	
V_{OH}	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$, $I_{OH} = -2\text{ mA}$		$V_{CC} - 2$		$V_{CC} - 2$		V	
	$V_{CC} = 4.5\text{ V}$	$I_{OH} = -3\text{ mA}$	2.4	3.2	2.4	3.2		
		$I_{OH} = -12\text{ mA}$	2					
V_{OL}	$V_{CC} = 4.5\text{ V}$	$I_{OL} = 48\text{ mA}$	0.3 0.55				V	
		$I_{OL} = 64\text{ mA}$			0.35 0.55			
I_I	Control inputs	$V_{CC} = 5.5\text{ V}$	$V_I = 7\text{ V}$	0.1		0.1		mA
	A or B ports		$V_I = 5.5\text{ V}$	0.1		0.1		
I_{IH}	Control inputs	$V_{CC} = 5.5\text{ V}$	$V_I = 2.7\text{ V}$	50		20		μA
	A or B ports‡			70		70		
I_{IL}	Control inputs	$V_{CC} = 5.5\text{ V}$	$V_I = 0.4\text{ V}$	-0.5		-0.5		mA
	A or B ports‡			-0.75		-0.75		
I_O^{\S}	$V_{CC} = 5.5\text{ V}$, $V_O = 2.25\text{ V}$		-50	-150	-50	-150	mA	
I_{CC}	$V_{CC} = 5.5\text{ V}$		Outputs high	62	97	62	97	mA
			Outputs low	95	143	95	143	
			Outputs disabled	79	123	79	123	

† All typical values are $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.

§ The output conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit output current, I_{OS} .

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$, $C_L = 50\text{ pF}$, $R_1 = 500\ \Omega$, $R_2 = 500\ \Omega$, $T_A = \text{MIN to MAX}^{\parallel}$				UNIT
			SN54AS245		SN74AS245		
			MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	2	9.5	2	7.5	ns
t_{PHL}			2	9	2	7	
t_{PZH}	\overline{OE}	A or B	2	11	2	9	ns
t_{PZL}			2	10.5	2	8.5	
t_{PHZ}	\overline{OE}	A or B	2	7.5	2	5.5	ns
t_{PLZ}			2	12	2	9.5	

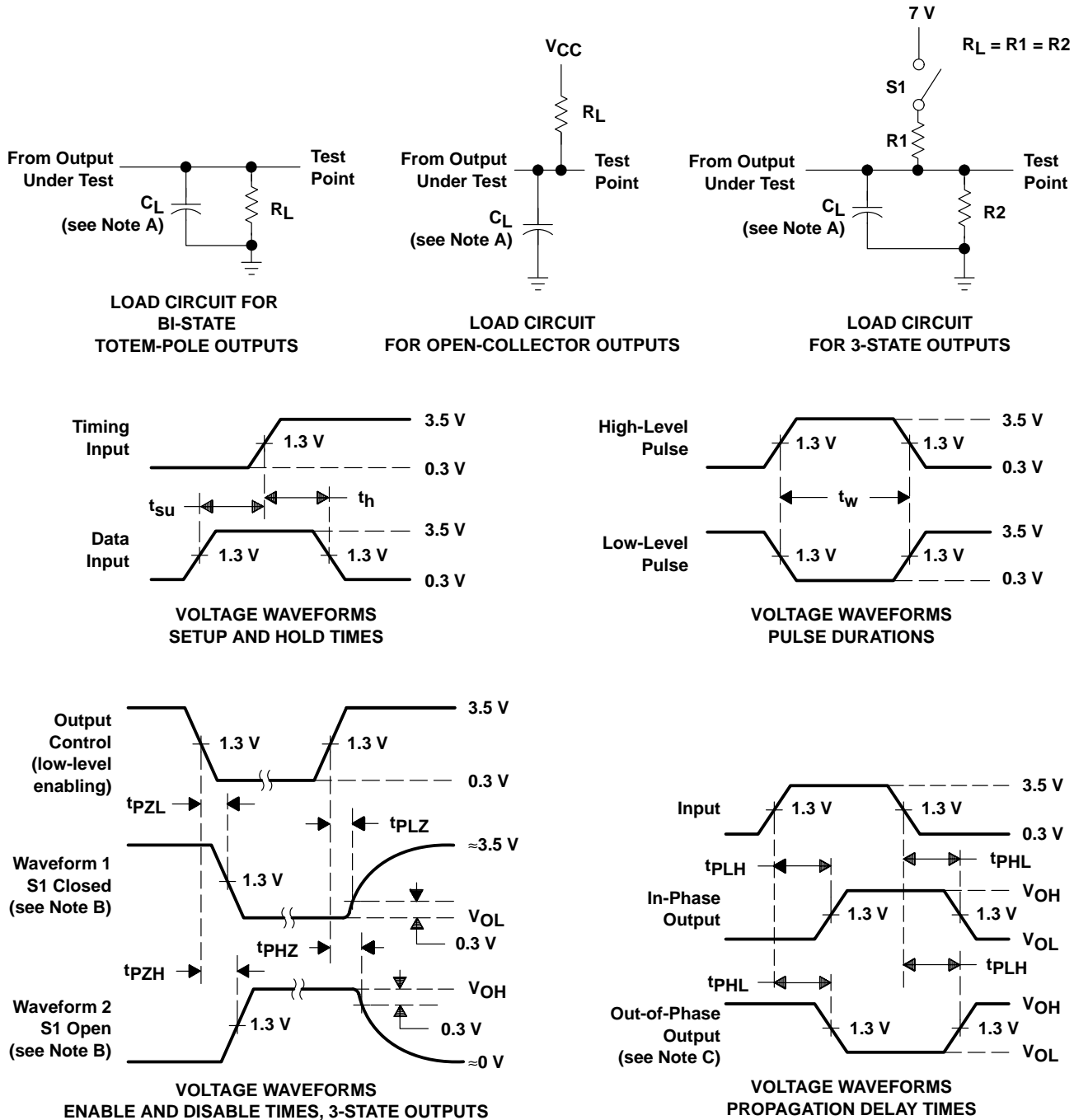
[¶] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



SN54ALS245A, SN54AS245, SN74ALS245A, SN74AS245
OCTAL BUS TRANSCEIVERS
WITH 3-STATE OUTPUTS

SDAS272A – NOVEMBER 1994 – REVISED JANUARY 2003

PARAMETER MEASUREMENT INFORMATION
SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
 D. All input pulses have the following characteristics: $PRR \leq 1$ MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
 E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
84030012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84030012A SNJ54ALS 245AFK	Samples
8403001RA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8403001RA SNJ54ALS245AJ	Samples
8403001SA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8403001SA SNJ54ALS245AW	Samples
SN54ALS245AJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54ALS245AJ	Samples
SN54AS245J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54AS245J	Samples
SN74ALS245A-1DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A-1	Samples
SN74ALS245A-1DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A-1	Samples
SN74ALS245A-1DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A-1	Samples
SN74ALS245A-1DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A-1	Samples
SN74ALS245A-1N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS245A-1N	Samples
SN74ALS245A-1NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS245A-1N	Samples
SN74ALS245A-1NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A-1	Samples
SN74ALS245ADBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	G245A	Samples
SN74ALS245ADBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	G245A	Samples
SN74ALS245ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A	Samples
SN74ALS245ADWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A	Samples
SN74ALS245ADWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ALS245ADWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A	Samples
SN74ALS245ADWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A	Samples
SN74ALS245AN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS245AN	Samples
SN74ALS245ANE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS245AN	Samples
SN74ALS245ANSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A	Samples
SN74ALS245ANSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A	Samples
SN74AS245DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS245	Samples
SN74AS245N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS245N	Samples
SN74AS245NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74AS245	Samples
SNJ54ALS245AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84030012A SNJ54ALS 245AFK	Samples
SNJ54ALS245AJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8403001RA SNJ54ALS245AJ	Samples
SNJ54ALS245AW	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8403001SA SNJ54ALS245AW	Samples
SNJ54AS245FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54AS 245FK	Samples
SNJ54AS245J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54AS245J	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54ALS245A, SN54AS245, SN74ALS245A, SN74AS245 :

● Catalog: [SN74ALS245A](#), [SN74AS245](#)

● Military: [SN54ALS245A](#), [SN54AS245](#)

NOTE: Qualified Version Definitions:

● Catalog - TI's standard catalog product

● Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS245A-1DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ALS245A-1NSR	SO	NS	20	2000	330.0	24.4	9.0	13.0	2.4	12.0	24.0	Q1
SN74ALS245ADBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74ALS245ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ALS245ANSR	SO	NS	20	2000	330.0	24.4	9.0	13.0	2.4	12.0	24.0	Q1
SN74AS245NSR	SO	NS	20	2000	330.0	24.4	9.0	13.0	2.4	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS245A-1DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS245A-1NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74ALS245ADBR	SSOP	DB	20	2000	367.0	367.0	38.0
SN74ALS245ADWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS245ANSR	SO	NS	20	2000	367.0	367.0	45.0
SN74AS245NSR	SO	NS	20	2000	367.0	367.0	45.0

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within Mil-Std 1835 GDFP2-F20

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

MECHANICAL DATA

NS (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - (C) Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - (D) The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW0020A



PACKAGE OUTLINE

SOIC - 2.65 mm max height

SOIC



NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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